

ABSTRACT

Copper Foil to be Used in Laminate Sheet

5 A copper alloy foil to be used in a printed board comprising a polyimide substrate is provided. The copper foil is not subjected to roughening plating and has hence fine surface roughness and can be directly bonded with the polyimide substrate. The copper alloy contains (a) one or more of the additive elements of from 0.01 to 2.0% of Cr and from 0.01 to 1.0% of Zr, or (b) from 1.0 to 4.8% of Ni and from 0.2 to 1.4% of Si. The
10 surface roughness in terms of the ten-point average surface-roughness (R_z) is $2\text{ }\mu\text{m}$ or less, the 180° peeling strength is 8.0N/cm or more. The alloy (a) has has 600N/mm² or more of tensile strength, and 50%ICAS or more of electric conductivity. The alloy (b) has has 650N/mm² or more of tensile strength, and 50%ICAS or more of electric conductivity.